# **Dual Multiplexer With Latch**

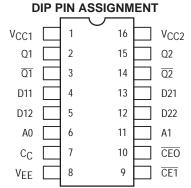
The MC10134 is a dual multiplexer with clocked D type latches. Each latch may be clocked separately by holding the common clock in the low state, and using the clock enable inputs for the clocking function. If the common clock is to be used to clock the latch, the clock enable  $(\overline{CE})$  inputs must be in the low state. In this mode, the enable inputs perform the function of controlling the common clock  $(C_C)$ .

The data select inputs determine which data input is enabled. A high (H) level on the A0 input enables data input D12 and a low (L) level on the A0 input enables data input D11. A high (H) level on the A1 input enables data input D22 and a low (L) level on the A1 input enables data input D21.

Any change on the data input will be reflected at the outputs while the clock is low. The outputs are latched on the positive transition of the clock. While the clock is in the high state, a change in the information present at the data inputs will not affect the output information.

- $P_D = 225 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 3.0 \text{ ns typ}$
- $t_r$ ,  $t_f = 2.5$  ns typ (20%–80%)

#### LOGIC DIAGRAM $V_{CC1} = PIN 1$ V<sub>CC2</sub> = PIN 16 VEE = PIN 8 Α1 11 D11 2 Q1 D12 CEO 10 3 Q1 CC15 02 CE<sub>1</sub> 9 D21 13 14 Q2 D22 12



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



#### ON Semiconductor

http://onsemi.com

#### MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620 MC10134L AWLYYWW



PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

#### **TRUTH TABLE**

С	A0	D11	D12	Q <sub>n+1</sub>
L	L	L	Х	L
L	L	Н	Χ	Н
L	Н	Х	L	L
L	Н	Χ	Н	Н
Н	Х	Х	Х	Qn

 $C = \overline{C}E + CC$ 

#### **ORDERING INFORMATION**

Device	Package	Shipping		
MC10134L	CDIP-16	25 Units / Rail		
MC10134P	PDIP-16	25 Units / Rail		
MC10134FN	PLCC-20	46 Units / Rail		

### **ELECTRICAL CHARACTERISTICS**

				Test Limits							
Characteristic		l I,	Pin Under	-30°C +25°C		+85°C		5°C			
		Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply D	rain Current	ΙE	8		60			55		60	mAdc
Input Current		linH	4 5 6 7 10		460 460 425 460 425			290 290 265 290 265		290 290 265 290 265	μAdc
		l <sub>inL</sub>	4*	0.5		0.5			0.3		μAdc
Output Voltage	Logic 1	Voн	2 2	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage	Logic 0	VOL	2 2	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdc
Threshold Volta	ge Logic 1	Vона	2 2	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdc
Threshold Volta	ge Logic 0	Vola	2 2		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vdc
Switching Times	s (50Ω Load)										ns
Propagation De	lay Data Clock Select	t <sub>4+2+</sub> t <sub>10-2+</sub> t <sub>6+2+</sub>	2 2 2	1.0 1.0 1.0	3.5 6.0 4.8	1.0 1.0 1.0		3.3 5.7 4.6	1.0 1.0 1.0	3.6 6.3 5.0	
Setup Time	Data Select	<sup>t</sup> setup <sup>t</sup> setup	2 2	2.5 3.5		2.5 3.5			2.5 3.5		
Hold Time	Data Select	<sup>t</sup> hold <sup>t</sup> hold	2 2	1.5 1.0		1.5 1.0			1.5 1.0		
Rise Time	(20 to 80%)	t <sub>2+</sub>	2	1.5	3.7	1.5		3.5	1.5	3.8	
Fall Time	(20 to 80%)	t <sub>2</sub> _	2	1.5	3.7	1.5		3.5	1.5	3.8	

<sup>\*</sup> All other inputs tested in the same manner.

### **ELECTRICAL CHARACTERISTICS** (continued)

		<u> </u>			TEST VO	LTAGE VALU	JES (Volts)		
		@ Test Te	mperature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	VIHAmin	V <sub>ILAmax</sub>	VEE	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST V	] ,, ,				
Characteri	istic	Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	VIHAmin	V <sub>ILAmax</sub>	VEE	(VCC)
Power Supply Drain C	Current	ΙΕ	8					8	1, 16
Input Current		linH	4 5 6 7 10	4 5 6 7 10				8 8 8	1, 16 1, 16 1, 16
		l <sub>inL</sub>	4*		4			8	1, 16
Output Voltage	Logic 1	Vон	2 2	4 5,6	6,7,10 7,10			8 8	1, 16 1, 16
Output Voltage	Logic 0	VOL	2 2	6	4,6,7,10 5,7,10			8 8	1, 16 1, 16
Threshold Voltage	Logic 1	Vона	2 2	6	6,7,10 7,10	4 5		8 8	1, 16 1, 16
Threshold Voltage	Logic 0	VOLA	2 2	6	6,7,10 7,10		4 5	8 8	1, 16 1, 16
Switching Times	(50Ω Load)			+1.11 V	+0.31 V	Pulse In	Pulse Out	–3.2 V	+2.0 V
Propagation Delay	Data Clock Select	t <sub>4+2+</sub> t <sub>10-2+</sub> t <sub>6+2+</sub>	2 2 2	4 5	6,7,10 7 7,10	4 10 6	2 2 2	8 8 8	1, 16 1, 16 1, 16
Setup Time	Data Select	<sup>t</sup> setup <sup>t</sup> setup	2 2	5	6,7 7,11	4,10 6,10	2 2	8 8	1, 16 1, 16
Hold Time	Data Select	<sup>t</sup> hold <sup>t</sup> hold	2 2	5	6,7 7,11	4,10 6,10	2 2	8 8	1, 16 1, 16
Rise Time	(20 to 80%)	t <sub>2+</sub>	2		6,7,10	4	2	8	1, 16
Fall Time	(20 to 80%)	t <sub>2</sub> _	2		6,7,10	4	2	8	1, 16

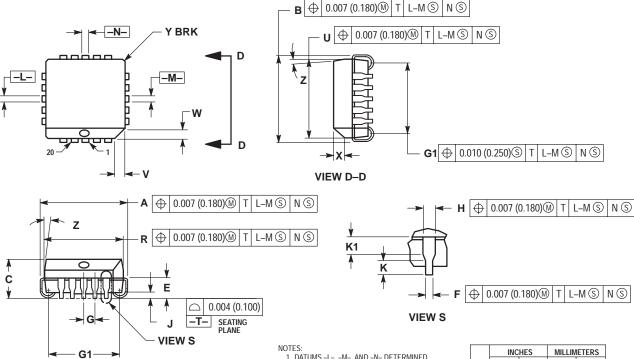
<sup>\*</sup> All other inputs tested in the same manner.

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 **ISSUE C** 



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- DATUMS -L-, -M-, AND -N- DETERMINED
   WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
  4. DIMENSIONING AND TOLERANCING PER ANSI

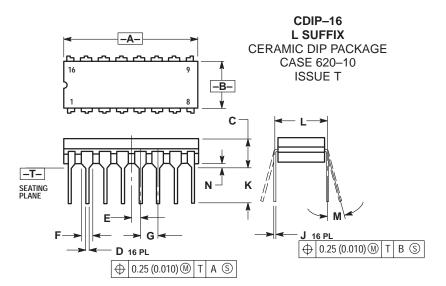
- 714.5M, 1982.

  5. CONTROLLING DIMENSION: INCH.

  6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO .012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES MILLIMETERS						
DIM	MIN	MAX	MIN	MAX			
Α	0.385	0.395	9.78	10.03			
В	0.385	0.395	9.78	10.03			
С	0.165	0.180	4.20	4.57			
Ε	0.090	0.110	2.29	2.79			
F	0.013	0.019	0.33	0.48			
G	0.050	BSC	1.27	BSC			
Н	0.026	0.032	0.66	0.81			
J	0.020		0.51				
K	0.025		0.64				
R	0.350	0.356	8.89	9.04			
U	0.350	0.356	8.89	9.04			
٧	0.042	0.048	1.07	1.21			
W	0.042	0.048	1.07	1.21			
Х	0.042	0.056	1.07	1.42			
Υ		0.020		0.50			
Z	2°	10°	2 °	10 °			
G1	0.310	0.330	7.88	8.38			
K1	0.040		1.02				

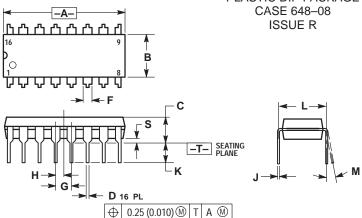
#### **PACKAGE DIMENSIONS**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Ε	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

# **Notes**

# **Notes**

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

#### PUBLICATION ORDERING INFORMATION

North America Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: ONlit@hibbertco.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor - European Support

**German Phone:** (+1) 303–308–7140 (M–F 2:30pm to 5:00pm Munich Time)

Email: ONlit-german@hibbertco.com

French Phone: (+1) 303–308–7141 (M–F 2:30pm to 5:00pm Toulouse Time)

Email: ONlit-french@hibbertco.com

English Phone: (+1) 303–308–7142 (M–F 1:30pm to 5:00pm UK Time)

Email: ONlit@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support

Phone: 303–675–2121 (Tue–Fri 9:00am to 1:00pm, Hong Kong Time) Toll Free from Hong Kong 800–4422–3781

Email: ONlit-asia@hibbertco.com

**JAPAN**: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda. Shinagawa–ku, Tokyo, Japan 141–8549

**Phone**: 81–3–5740–2745 **Email**: r14525@onsemi.com

Fax Response Line: 303-675-2167

800-344-3810 Toll Free USA/Canada

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.